

NP35N04YLG

R07DS0182EJ0100

Rev.1.00

Oct 22, 2010

MOS FIELD EFFECT TRANSISTOR

Description

The NP35N04YLG is N-channel MOS Field Effect Transistor designed for high current switching applications.

Features

- Low on-state resistance
 - $R_{DS(on)} = 9.7 \text{ m}\Omega \text{ MAX.}$ ($V_{GS} = 10 \text{ V}$, $I_D = 17.5 \text{ A}$)
 - $R_{DS(on)} = 15 \text{ m}\Omega \text{ MAX.}$ ($V_{GS} = 5 \text{ V}$, $I_D = 17.5 \text{ A}$)
- Logic level drive type
- Gate to Source ESD protection diode built in
- Designed for automotive application and AEC-Q101 qualified

Ordering Information

Part No.	LEAD PLATING	PACKING	Package
NP35N04YLG -E1-AY ^{*1}	Pure Sn (Tin)	Tape 2500 p/reel	8-pin HSON, Taping (E1 type)
NP35N04YLG -E2-AY ^{*1}			8-pin HSON, Taping (E2 type)

Note: ^{*1}. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$)

Item	Symbol	Ratings	Unit
Drain to Source Voltage ($V_{GS} = 0 \text{ V}$)	V_{DSS}	40	V
Gate to Source Voltage ($V_{DS} = 0 \text{ V}$)	V_{GSS}	± 20	V
Drain Current (DC) ($T_C = 25^\circ\text{C}$)	$I_{D(DC)}$	± 35	A
Drain Current (pulse) ^{*1}	$I_{D(pulse)}$	± 105	A
Total Power Dissipation ($T_C = 25^\circ\text{C}$)	P_{T1}	77	W
Total Power Dissipation ($T_A = 25^\circ\text{C}$) ^{*2}	P_{T2}	1.0	W
Channel Temperature	T_{ch}	175	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +175	$^\circ\text{C}$
Repetitive Avalanche Current ^{*3}	I_{AR}	22	A
Repetitive Avalanche Energy ^{*3}	E_{AR}	48	mJ

Thermal Resistance

Channel to Case Thermal Resistance	$R_{th(ch-C)}$	1.95	$^\circ\text{C/W}$
Channel to Ambient Thermal Resistance ^{*2}	$R_{th(ch-A)}$	150	$^\circ\text{C/W}$

Notes: ^{*1}. $T_C = 25^\circ\text{C}$, $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

^{*2}. Mounted on glass epoxy substrate of 40 mm x 40 mm x 0.8 mm

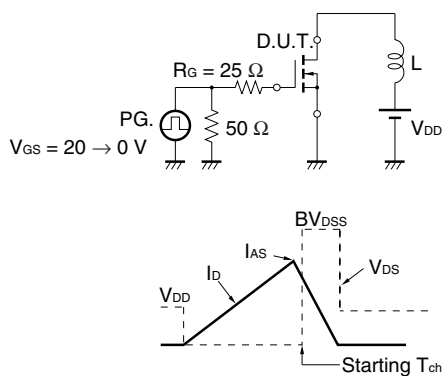
^{*3}. $T_{ch(peak)} \leq 150^\circ\text{C}$, $R_G = 25 \Omega$

Electrical Characteristics ($T_A = 25^\circ\text{C}$)

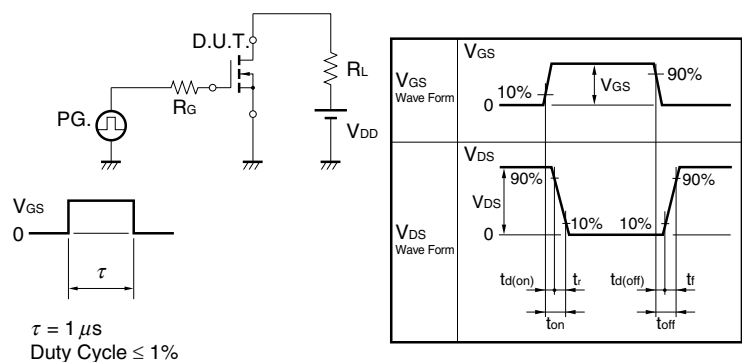
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I_{DSS}			1	μA	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}$
Gate Leakage Current	I_{GSS}			± 10	μA	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$
Gate to Source Threshold Voltage	$V_{GS(th)}$	1.4	1.9	2.5	V	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$
Forward Transfer Admittance ^{*1}	$ y_{fs} $	15	30		S	$V_{DS} = 5\text{ V}, I_D = 17.5\text{ A}$
Drain to Source On-state Resistance ^{*1}	$R_{DS(on)1}$		7.8	9.7	$\text{m}\Omega$	$V_{GS} = 10\text{ V}, I_D = 17.5\text{ A}$
Drain to Source On-state Resistance ^{*1}	$R_{DS(on)2}$		9.6	15	$\text{m}\Omega$	$V_{GS} = 5\text{ V}, I_D = 17.5\text{ A}$
Input Capacitance	C_{iss}		1900	2850	pF	$V_{DS} = 25\text{ V},$ $V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$
Output Capacitance	C_{oss}		190	290	pF	
Reverse Transfer Capacitance	C_{rss}		120	220	pF	
Turn-on Delay Time	$t_{d(on)}$		13	26	ns	$V_{DD} = 20\text{ V}, I_D = 17.5\text{ A},$ $V_{GS} = 10\text{ V},$ $R_G = 0\text{ }\Omega$
Rise Time	t_r		11	27	ns	
Turn-off Delay Time	$t_{d(off)}$		43	86	ns	
Fall Time	t_f		5	12	ns	$V_{DD} = 32\text{ V},$ $V_{GS} = 10\text{ V},$ $I_D = 35\text{ A}$
Total Gate Charge	Q_G		34	51	nC	
Gate to Source Charge	Q_{GS}		6		nC	
Gate to Drain Charge	Q_{GD}		10		nC	$I_F = 35\text{ A}, V_{GS} = 0\text{ V}$
Body Diode Forward Voltage ^{*1}	$V_{F(S-D)}$		0.91	1.5	V	
Reverse Recovery Time	t_{rr}		27		ns	
Reverse Recovery Charge	Q_{rr}		25		nC	$di/dt = 100\text{ A}/\mu\text{s}$

Note: *1. Pulsed

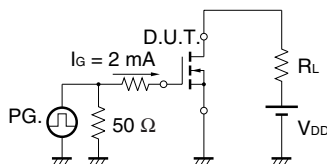
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME

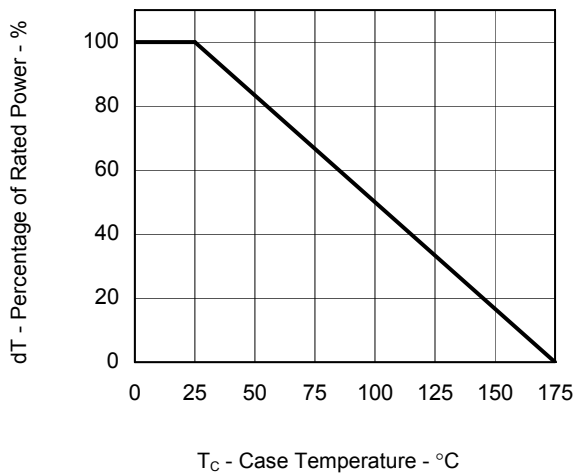


TEST CIRCUIT 3 GATE CHARGE

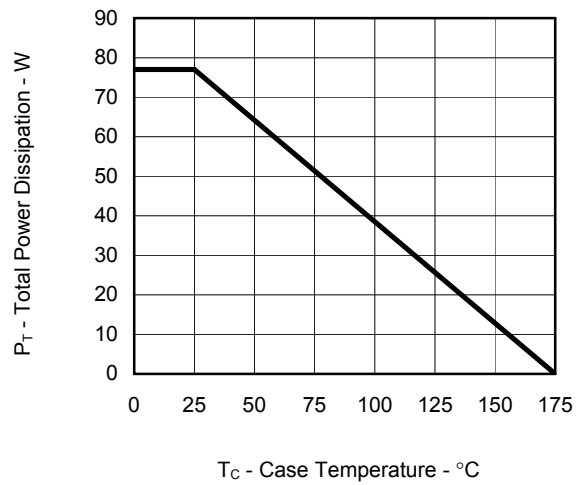


Typical Characteristics ($T_A = 25^\circ\text{C}$)

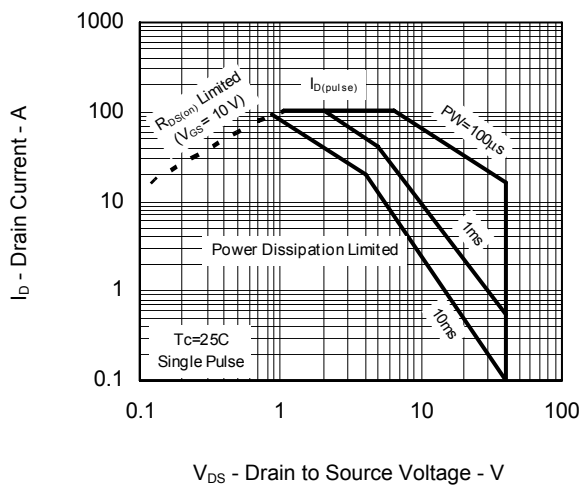
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



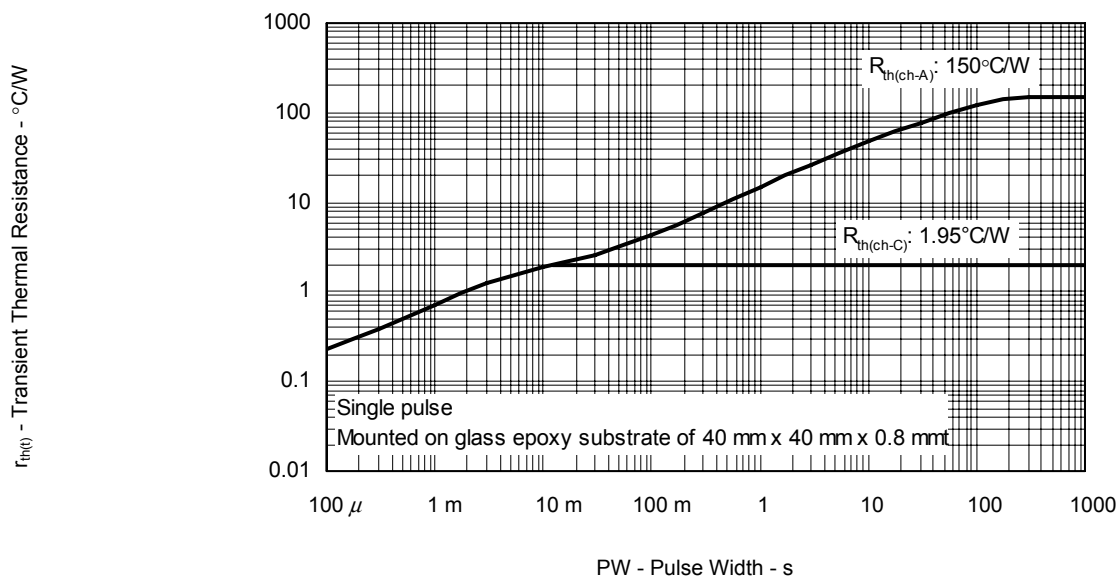
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

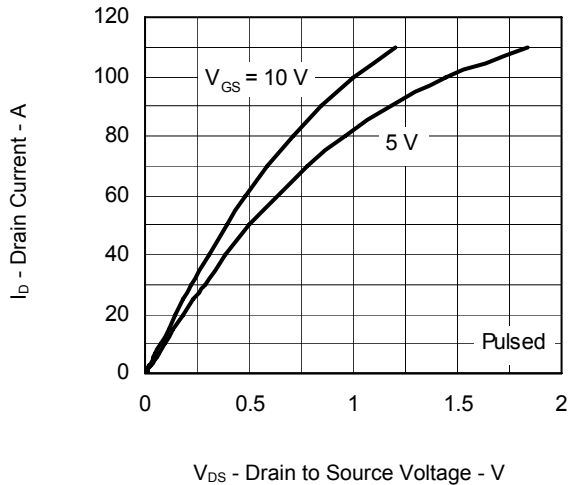


FORWARD BIAS SAFE OPERATING AREA

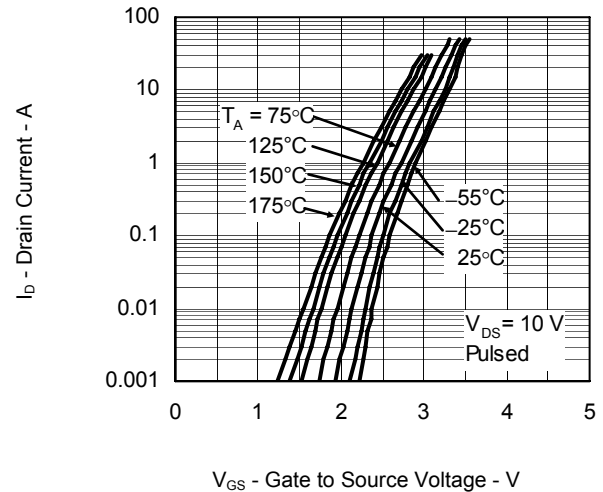
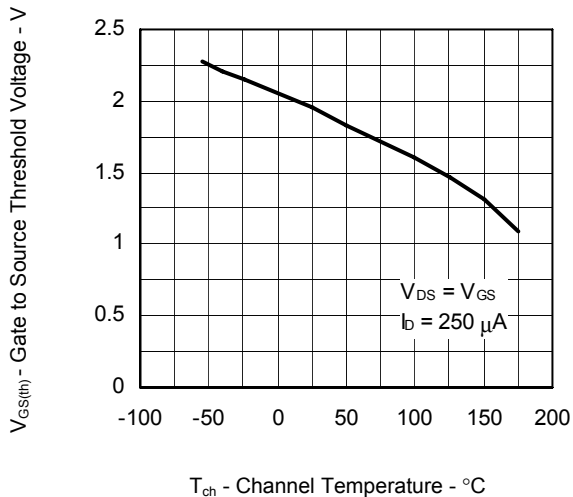
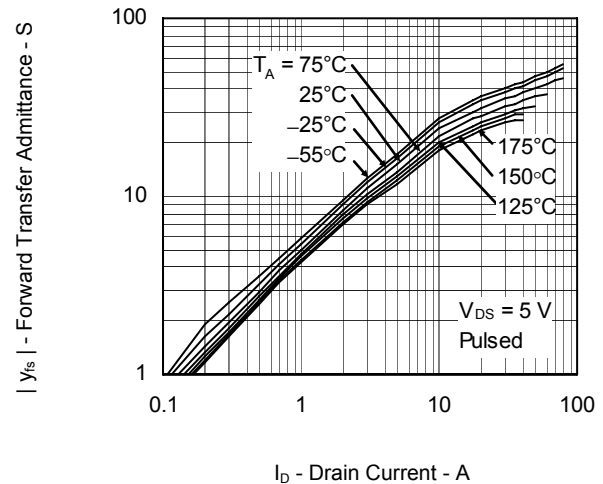
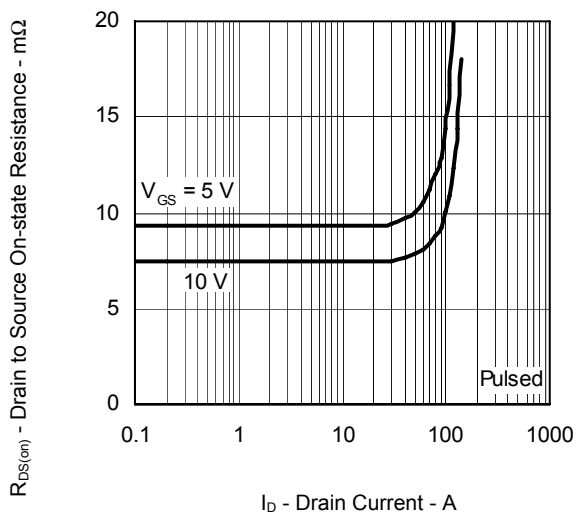
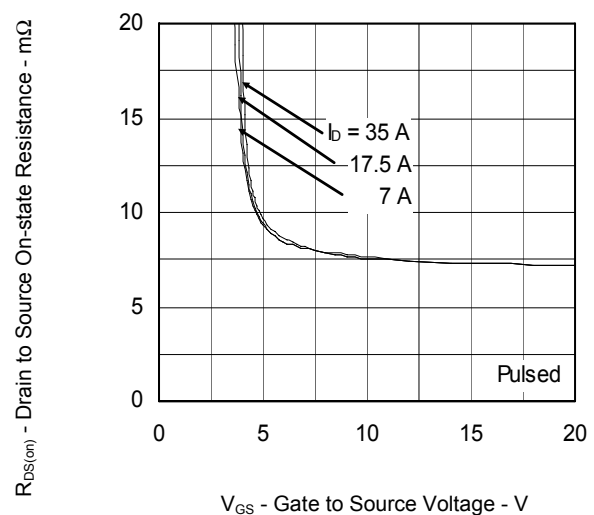


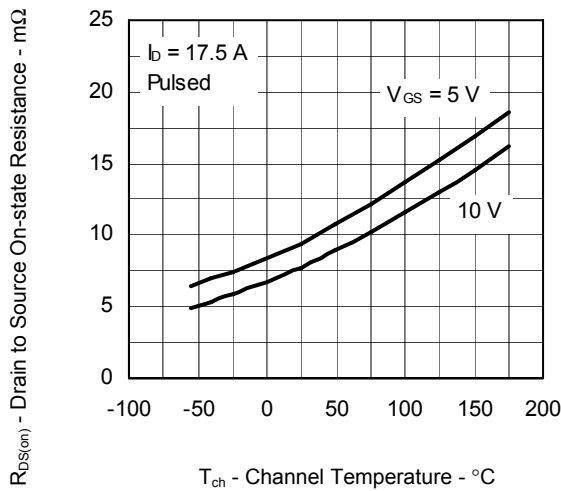
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



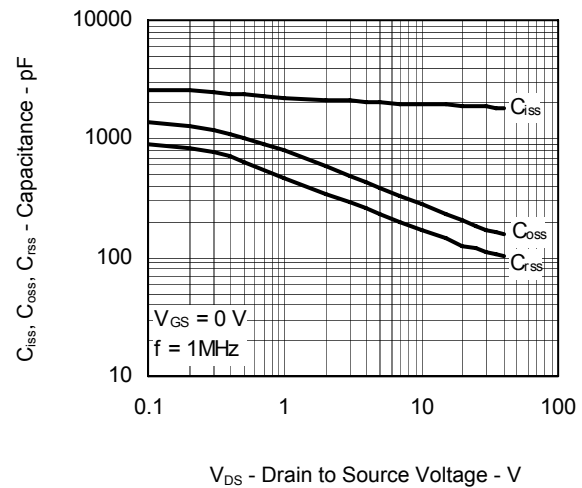
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE

FORWARD TRANSFER CHARACTERISTICS

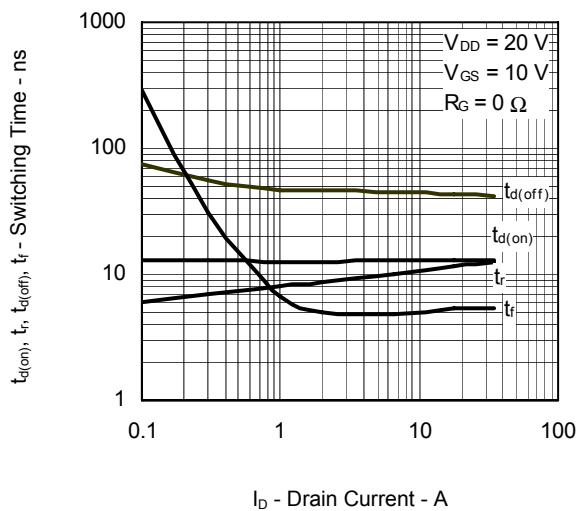
GATE TO SOURCE THRESHOLD VOLTAGE
vs. CHANNEL TEMPERATUREFORWARD TRANSFER ADMITTANCE vs. DRAIN
CURRENTDRAIN TO SOURCE ON-STATE RESISTANCE vs.
DRAIN CURRENTDRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE

DRAIN TO SOURCE ON-STATE RESISTANCE vs.
CHANNEL TEMPERATURE

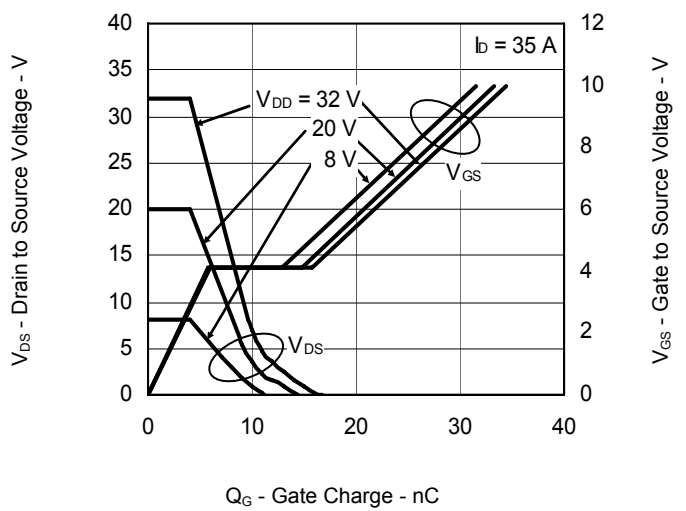
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



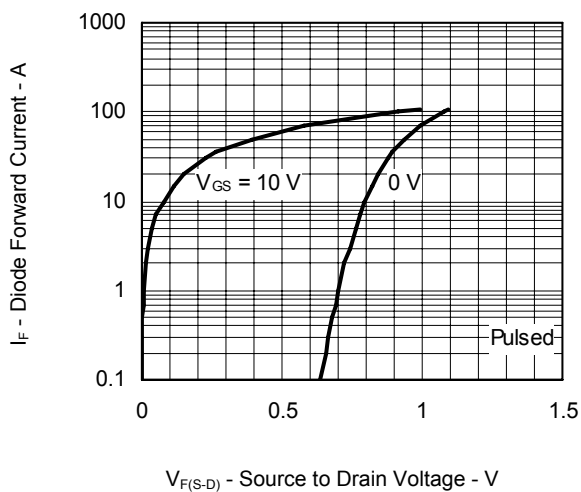
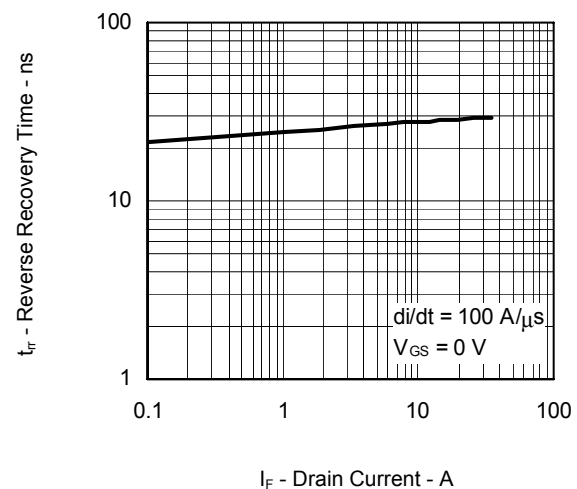
SWITCHING CHARACTERISTICS



DYNAMIC INPUT/OUTPUT CHARACTERISTICS

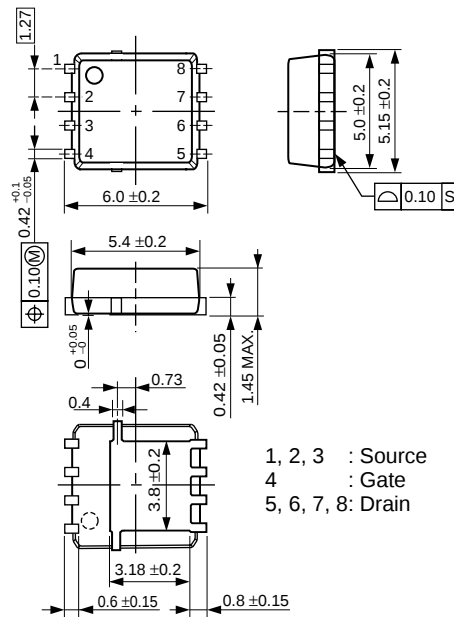


SOURCE TO DRAIN DIODE FORWARD VOLTAGE

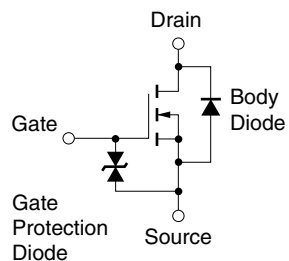
REVERSE RECOVERY TIME vs.
DRAIN CURRENT

Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



Equivalent Circuit



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Revision History	NP35N04YLG
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Rev.	Date	Description	
		Page	Summary
1.00	Oct 22, 2010	–	First Edition Issued

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Renesas Electronics America Inc.

2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited

1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.

7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited

Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.

7F, No. 363 Fu Shing North Road Taipei, Taiwan, R.O.C.
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

1 harbourFront Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.

11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141